



Material Content Data Sheet



Sales Product Name		IDH10SG60C		Issued		29. August 2013		
MA#		MA000629888						
Package		PG-TO220-2-1		Weight*		1966.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.082	0.00		41	
	non noble metal	arsenic	7440-38-2	0.001	0.00		0	
	inorganic material	siliconcarbide	409-21-2	2.502	0.13	0.13	1272	1313
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		383	
	inorganic material	phosphorus	7723-14-0	0.226	0.01		115	
	non noble metal	copper	7440-50-8	751.797	38.22	38.27	382207	382705
wire	non noble metal	aluminium	7429-90-5	1.248	0.06	0.06	635	635
encapsulation	organic material	carbon black	1333-86-4	9.082	0.46		4617	
	plastics	epoxy resin	-	99.900	5.08		50789	
	inorganic material	silicondioxide	60676-86-0	496.473	25.24	30.78	252404	307810
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7365	7365
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	0	101
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		90	
	non noble metal	iron	7439-89-6	0.590	0.03		300	
	non noble metal	copper	7440-50-8	589.466	29.97	30.01	299681	300071
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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